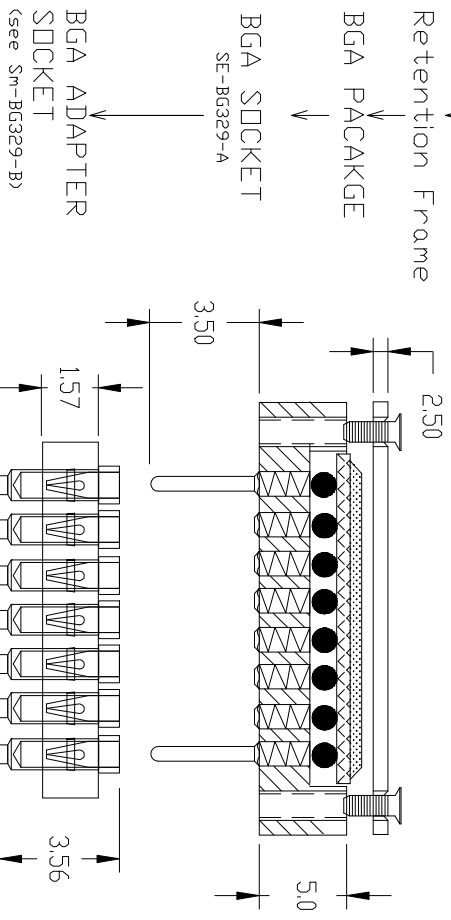


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REV.	REV.	DESCRIPTION OF CHANGE	EFFECTIVE DATE	ORIGINATOR
0	0	Initial	4/30/99	Ray Kung

ASSEMBLY FLOW



Solder past thickness need to be at least 0.20mm(or0008 inch) in order to have reliable solder joint

Please see detail drawing for part number

Note: Dim: mm

- To remove BGA socket from adapter socket, Use removal tool from Mill-Max
- Mill-Max phone: 516-922-6000

ACTEL CONFIDENTIAL

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		PRODUCTION		ACTEL CORP. 855 E ARQUES AVE SUNNYVALE CA 94086	
DECIMAL	±1°	APPROVALS	DATE	TITLE	329-31x31mm, 1.27mm E-TEC BGA SOCKET (329 BGA E-TEC Socket Assembly)
X.X ±0.10		DRAWN	4/27/99	SIZE	B
X.XX ±0.05		CHECKED		VENDOR NAME	e-tec
X.XXX ±0.03		ENGINEER		VENDOR DWG. NUMBER	1-07-09037
		RELEASED		VENDOR Dwg. NUMBER	
				SCALE: NONE	SHEET 2 OF 2